

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No. 50169/105/ENPO

In re patent application of

Assistant Commissioner for Patents

Wallace T.Y. TANG

Serial No. 08/401,229

Filed: March 9, 1995

Washington, D.C. 20231

Group Art Unit: 2501

Examiner: J. Lee

IN-SITU REAL-TIME MONITORING TECHNIQUE AND APPARATUS

FOR ENDPOINT DETECTION OF THIN FILMS DURING

CHEMICAL/MECHANICAL POLISHING PLANARIZATION

AMENDMENT AND REQUEST FOR RECONSIDERATION UNDER 37 C.F.R. § 1.111

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DEU 29 1775

GROUP 2500

sir:

For:

In response to the outstanding Office Action mailed on July 12, 1995, please amend the above-identified application as follows:

IN THE SPECIFICATION

On page 13, line 22, change "8" to --11--.
On page 14, line 22, change "8" to --11--.

IN THE CLAIMS

Please rewrite the following claim:

(amended) An apparatus for monitoring thickness change in a film on a substrate comprising

- (i) a bifurcated fiber-optic cable having a common leg and two bifurcated legs,
 - (ii) a rotating fiber-optic cable with two ends,
 - (iii) a light source,
- (iv) means for analyzing a light signal to determine thickness change and stopping thickness change when the thickness reaches a predetermined endpoint, and

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